
Study on Recovery System for Perfluorocarbon gases

Junyoung Park ¹, Byoungmoon Oh ¹, Kwangjin Oh ¹, Yoonjong kim ¹, Youngheum Yeon ¹, and Kyongnam Kim ¹

¹*Department of Advanced Materials Engineering, Daejeon University, Korea, Korea, Republic of*

In general, PFC gases with a very high GWP(Global Warming Potential) are used to remove residues generated through typical etching and CVD(Chemical Vapor Deposition) processes in display manufacturing including semiconductors. In recent years, the semiconductor manufacturing process has been progressing with high capacity and high integration according to the vertical lamination structure, and the PFC(Perfluorocarbon) gas used per unit area of the wafer has been explosively increased due to the increase of the high aspect ratio process and the patterning process. These PFC gases are chemically very stable and cannot be decomposed easily, which has a large impact on climate change and causes global warming. For this reason, much research is needed on the development of alternative precursors like liquid precursor with low GWP and recovery systems that can minimize the emission of by-products with high GWP and additional air pollutants generated during gas decomposition.

In this study, a recovery system for cooling and condensing high purity PFC gas used in semiconductor processing was developed and basic research on condensation and recovery was conducted. In addition, the study on the analysis of recovered gas components and the improvement of recovery efficiency by re-vaporizing the condensed gas has been studied in parallel.

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